

18-Line SCSI Terminator

FEATURES

- Complies with SCSI, SCSI-2, SCSI-3, SPI and FAST-20 Standards
- 2pF Channel Capacitance During Disconnect
- 50 μ A Supply Current in Disconnect Mode
- 110 Ω Termination
- SCSI Hot Plugging Compliant, 10nA Typical
- +400mA Sinking Current for Active Negation
- -650mA Sourcing Current for Termination
- Trimmed Impedance to 5%
- Thermal Shutdown
- Current Limit

DESCRIPTION

The UCC5618 provides 18 lines of active termination for a SCSI (Small Computers Systems Interface) parallel bus. The SCSI standard recommends and Fast-20 (Ultra) requires active termination at both ends of the cable.

Pin for pin compatible with the UC5601 and UC5608, the UCC5618 is ideal for high performance 5V SCSI systems, T_{mpwr} 4.0-5.25V. During disconnect the supply current is only 50 μ A typical, which makes the IC attractive for lower powered systems.

The UCC5618 is designed with a low channel capacitance of 2pF, which eliminates effects on signal integrity from disconnected terminators at interim points on the bus.

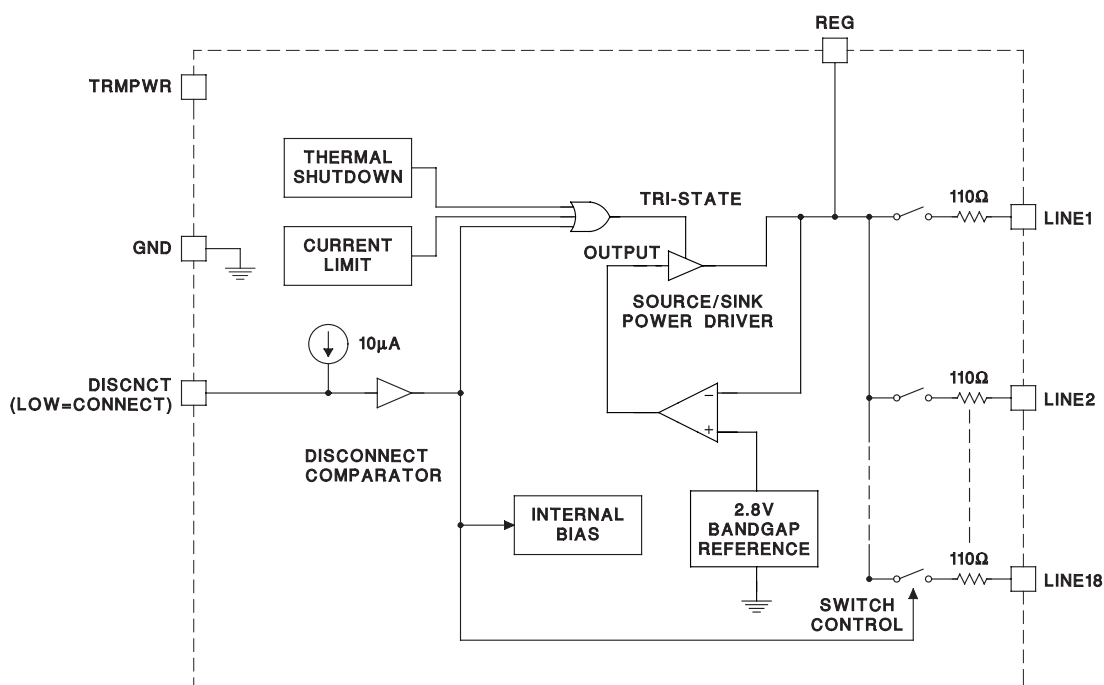
The power amplifier output stage allows the UCC5618 to source full termination current and sink active negation current when all termination lines are actively negated.

The UCC5618, as with all Unitrode terminators, is completely hot pluggable and appears as high impedance at the terminating channels with $TRMPWR=0V$ or open.

Internal circuit trimming is utilized, first to trim the 110 Ω impedance, and then most importantly, to trim the output current as close to the max SCSI-3 spec as possible, which maximizes noise margin in fast SCSI operation.

This device is offered in low thermal resistance versions of the industry standard 28 pin wide body SOIC, TSSOP and PLCC.

BLOCK DIAGRAM



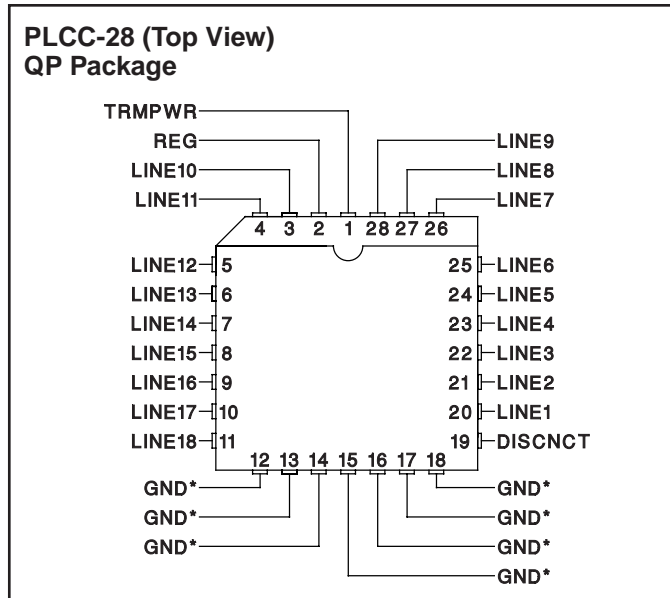
Patented Circuit Design

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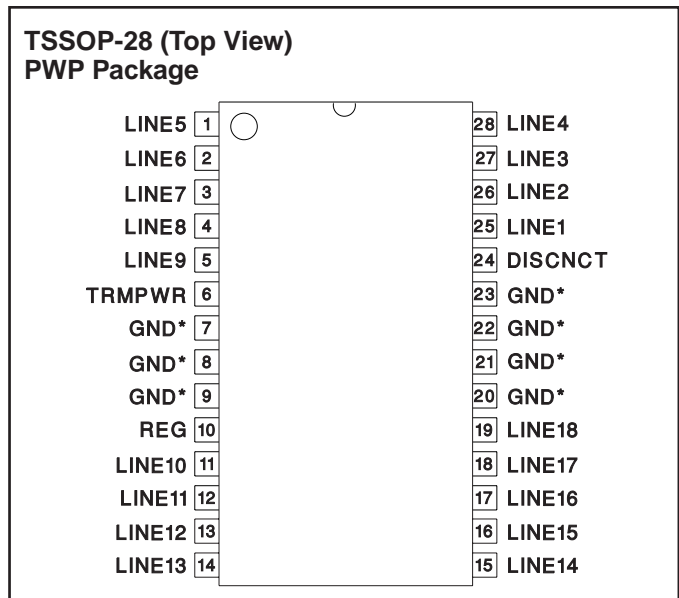
ABSOLUTE MAXIMUM RATINGS

TEMPWR. +7V
 Signal Line Voltage 0V to +7V
 Regulator Output Current 1A
 Storage Temperature -65°C to +150°C
 Operating Junction Temperature -55°C to +150°C
 Lead Temperature (Soldering, 10 Seconds) 300°C

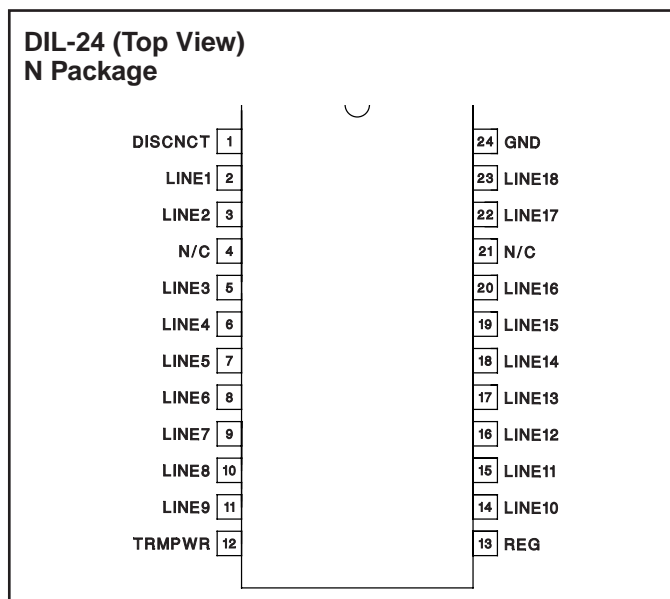
All currents are positive into, negative out of the specified terminal. Consult Packaging Section of Databook for thermal limitations and considerations of packages.

CONNECTION DIAGRAMS

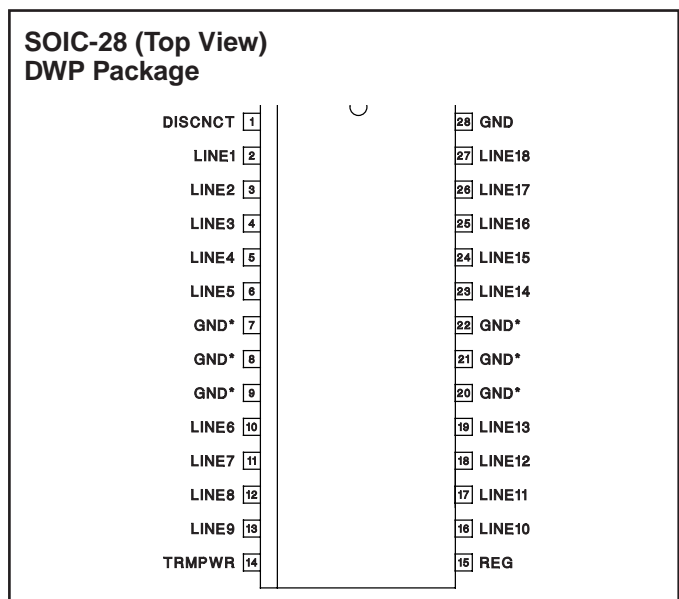
* DWP package pins 12–18 serve as both heatsink and signal ground.



* PWP package pin 23 serves as signal ground; pins 7, 8, 9, 20, 21, and 22 serve as heatsink ground.



Note: Drawings are not to scale.



* DWP package pin 28 serves as signal ground; pins 7, 8, 9, 20, 21, 22 serve as heatsink/ground.

ELECTRICAL CHARACTERISTICS: Unless otherwise stated these specifications apply for $T_A = 0^\circ\text{C}$ to 70°C , $\text{TRMPWR} = 4.75\text{V}$, $\text{DISCNCT} = 0\text{V}$, $T_A = T_J$.

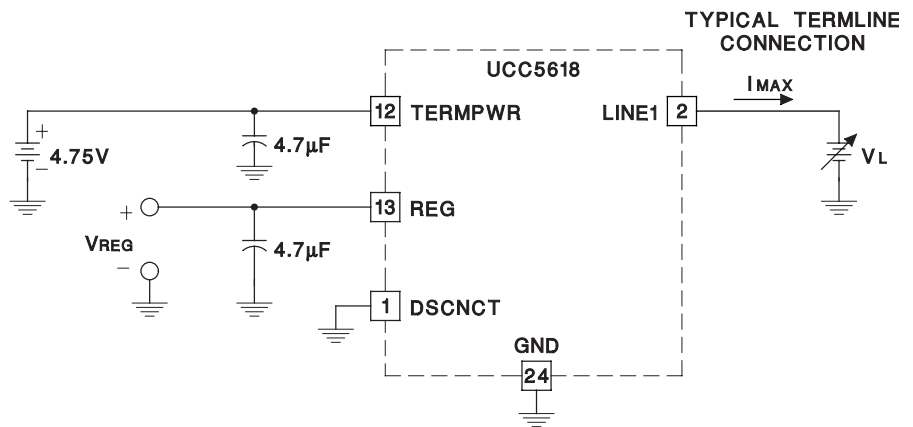
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Supply Current Section					
TERMPWR Supply Current	All Termination Lines = Open		1	2	mA
	All Termination Lines = 0.2V		420	440	mA
Power Down Mode	DISCNCT = TRMPWR		50	100	μA
Output Section (Termination Lines)					
Termination Impedance	See Figure 1	104.5	110	115.5	Ω
Output High Voltage	$V_{\text{TRMPWR}} = 4\text{V}$ (Note 1)	2.6	2.8	3	V
Max Output Current	$V_{\text{LINE}} = 0.2\text{V}$, $T_J = 25^\circ\text{C}$	-22.1	-23.3	-24	mA
	$V_{\text{LINE}} = 0.2\text{V}$	-20.7	-23.3	-24	mA
	$V_{\text{LINE}} = 0.2\text{V}$, $\text{TERMPWR} = 4\text{V}$, $T_J = 25^\circ\text{C}$ (Note 1)	-21	-23.3	-24	mA
	$V_{\text{LINE}} = 0.2\text{V}$, $\text{TRMPWR} = 4\text{V}$ (Note 1)	-20	-23	-24	mA
	$V_{\text{LINE}} = 0.5\text{V}$			-22.4	mA
Output Leakage	DISCNCT = 2.4V, TRMPWR = 0V to 5.25V, REG = 0.2V, $V_{\text{LINE}} = 5.25\text{V}$		10	400	nA
Output Capacitance	DISCNCT = 2.4V (Note 2)		2	3.5	pF
Regulator Section					
Regulator Output Voltage		2.6	2.8	3	V
Drop Out Voltage	All Termination Lines = 0.2V		0.4	0.8	V
Short Circuit Current	$V_{\text{REG}} = 0\text{V}$	-475	-650	-950	mA
Sinking Current Capability	$V_{\text{REG}} = 3.5\text{V}$	200	400	800	mA
Thermal Shutdown			170		$^\circ\text{C}$
Thermal Shutdown Hysteresis			10		$^\circ\text{C}$
Disconnect Section					
Disconnect Threshold		0.8	1.5	2	V
Input Current	DISCNCT = 0V		-10	-30	μA

Note 1: Measuring each termination line while other 17 are low (0.2V).

Note 2: Guaranteed by design. Not 100% tested in production.

Procedure:

- 1) Measure V_{REG} N.L.
- 2) Set $V_L = 0.2\text{V}$
- 3) Measure I_{MAX} at 0.2V
- 4) Impedance = $\frac{V_{\text{REG N.L.}} - 0.2\text{V}}{I_{\text{MAX}}}$



UDG-96102-1

Figure 1. Termline Impedance Measurement Circuit

PIN DESCRIPTIONS

DISCNCT: Taking this pin high or leaving it open causes the 18 channels to become high impedance and the chip to go into low-power mode; a low state allows the channels to provide normal termination.

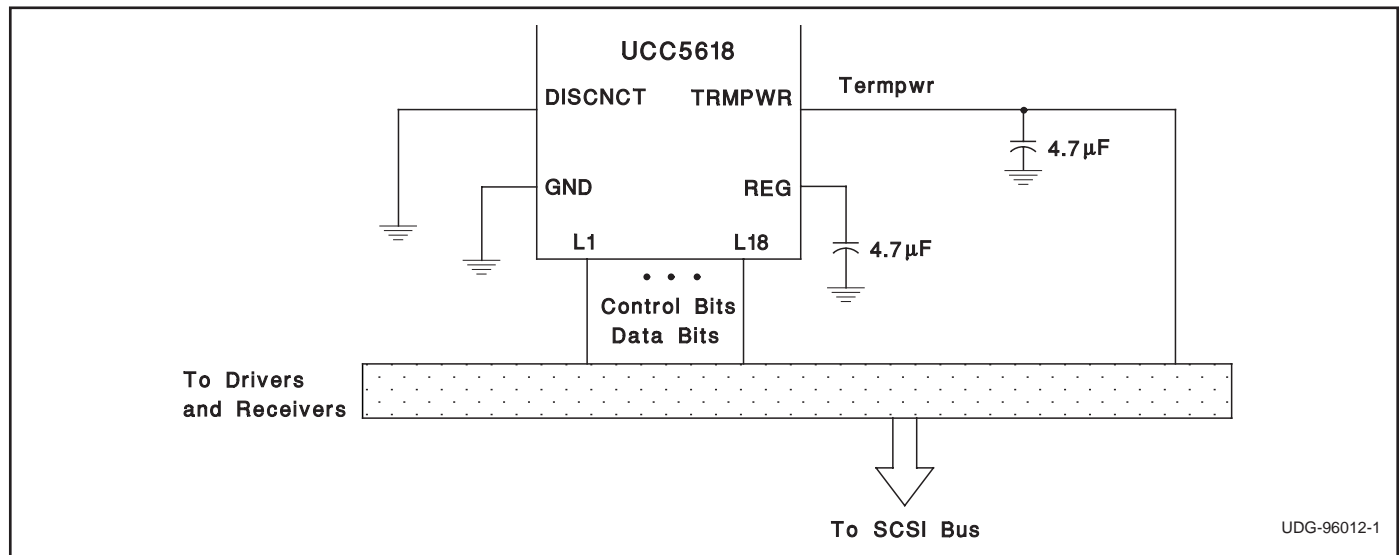
GND: Ground reference for the IC.

LINE1–LINE18: 110Ω termination channels.

REG: Output of the internal 2.8V regulator.

TRMPWR: Power for the IC.

APPLICATION INFORMATION



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
UCC5618DWP	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
UCC5618DWPG4	ACTIVE	SOIC	DW	28	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
UCC5618DWPTR	ACTIVE	SOIC	DW	28	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
UCC5618DWPTRG4	ACTIVE	SOIC	DW	28	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
UCC5618PWP	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
UCC5618PWPG4	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
UCC5618PWPTR	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
UCC5618PWPTRG4	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
UCC5618QP	ACTIVE	PLCC	FN	28	37	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UCC5618DWPTR	SOIC	DW	28	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1
UCC5618PWPTR	TSSOP	PW	28	2000	330.0	16.4	7.1	10.4	1.6	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UCC5618DWPTR	SOIC	DW	28	1000	367.0	367.0	55.0
UCC5618PWPTR	TSSOP	PW	28	2000	367.0	367.0	38.0

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